

--This application is a continuation of co-pending patent application having Serial No. 09/870,044, filed May 29, 2001, <sup>PT 6,635,513</sup> which is hereby fully incorporated herein by reference. Benefit of all earlier filing dates is claimed for all common subject matter.--

In the claims:

Please amend the claims as shown below.

Please cancel claims 8-12.

Please add the following claims.

21. (New) A method for providing support to a substrate, the method comprising:
- attaching a component to an electrical contact area on a first side of the substrate; and
  - attaching a pre-curved bolster plate on a second side of the substrate, the pre-curved bolster plate having a pre-calculated radius of curvature prior to attachment to the second side of the substrate.
22. (New) The method of claim 21, wherein the component comprises a land grid array (LGA) component.
23. (New) The method of claim 21, wherein the substrate is selected from a group of substrates consisting of: a